

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yi Guo</td> <td>03/11/2010</td> </tr> <tr> <td>Zhendong Liu</td> <td>03/11/2010</td> </tr> <tr> <td>Arun Reddy</td> <td>03/11/2010</td> </tr> <tr> <td>Guangyun Zhang</td> <td>03/11/2010</td> </tr> </tbody> </table>		Name	Execution Date	Yi Guo	03/11/2010	Zhendong Liu	03/11/2010	Arun Reddy	03/11/2010	Guangyun Zhang	03/11/2010
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<b>RECEIVING PARTY DATA</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Rohm and Haas Electronic Materials CMP Holdings, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>451 Bellevue Road</td> </tr> <tr> <td>City:</td> <td>Newark</td> </tr> <tr> <td>State/Country:</td> <td>DELAWARE</td> </tr> <tr> <td>Postal Code:</td> <td>19713</td> </tr> </table>		Name:	Rohm and Haas Electronic Materials CMP Holdings, Inc.	Street Address:	451 Bellevue Road	City:	Newark	State/Country:	DELAWARE	Postal Code:	19713
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<b>CORRESPONDENCE DATA</b>											
Fax Number: (302)283-2144 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 302-456-6622 Email: pconnell@dow.com Correspondent Name: Patricia Connell Address Line 1: 451 Bellevue Road Address Line 4: Newark, DELAWARE 19713											
ATTORNEY DOCKET NUMBER:	69639										
NAME OF SUBMITTER:	Patricia Connell										
Total Attachments: 2 source=69639 Assignment#page1.tif											

CH \$40.00 12724990

**501303549**

**PATENT**  
**REEL: 025053 FRAME: 0946**



**ASSIGNMENT OF PATENT APPLICATION**

We/I, the undersigned

Yi Guo, Zhendong Liu, Kancharla-Arun Kumar Reddy, and Guangyun Zhang


Hereby declare that

We/I are true and first inventor(s) of an invention relating to

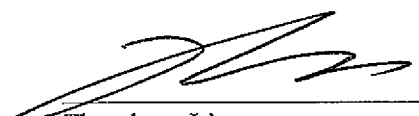
**METHOD OF POLISHING A SUBSTRATE COMPRISING POLYSILICON AND AT LEAST ONE OF SILICON OXIDE AND SILICON NITRIDE**

which is disclosed in an application for Letters Patent in the United States of America, executed the 11<sup>th</sup> day of March, 2010 (Case No. 69639); and, for valuable consideration, the receipt and adequacy of which is hereby acknowledged and in fulfillment of our pre-existing obligation of assignment, we hereby sell, assign and transfer unto Rohm and Haas Electronic Materials CMP Holdings, Inc., a corporation organized and existing under the laws of the State of Delaware in the United States of America and having its mailing address at 451 Bellevue Road, Newark, Delaware, hereinafter referred to as the assignee, the entire right, title, and interest in and to the aforesaid application for Letters Patent, including any priority rights derived from the aforesaid application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, and the entire right, title and interest in and to any and all our inventions, whether joint or sole, disclosed in the aforesaid application for Letters Patent, and in and to any and all applications for letters Patent for any such inventions in any country whatsoever, and in and to any and all patents for any such inventions in any country whatsoever, with the sole right to file such applications in its name or ours, including the sole right to file such applications under the aforesaid International Convention, together with the sole right to have said patents granted in its name or ours and to enforce said patents and to sue for and recover profits and damages for any and all infringements thereof, and hereby agree, whenever requested, to communicate to us respecting said inventions, to testify in any legal proceeding, to execute all applications, papers, or instruments necessary or required by said assignee, its successors, assigns, and legal representatives to carry into effect any of the provisions of this instrument, and generally to do everything possible to aid said assignee, its successors, assigns and legal representatives to obtain and enforce proper patent protection for said inventions in any and all countries.

IN WITNESS WHEREOF, We have hereunto signed our names on the day and year set forth below.

  
\_\_\_\_\_  
Yi Guo

03/11/2010  
\_\_\_\_\_  
DATE

  
\_\_\_\_\_  
Zhendong Liu

Mar. 11, 2010  
\_\_\_\_\_  
DATE



Arun Reddy

3/11/2010

DATE



Guangyun Zhang

3/11/10

DATE